

# New Ideas on Detector Technology for the ILC Experiments

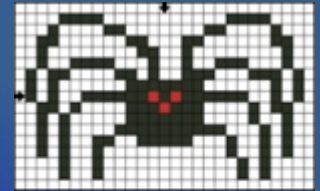
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on behalf of the ILC International Development  
Team Detector and Physics Group

30<sup>th</sup> International Symposium on Lepton Photon Interactions (LP2021)  
Online, Manchester, UK, Jan. 10-14, 2022

# Many forms of Linear Collider Detector R&D efforts:

Scintillator  
ECAL



SPiDeR

RPC DHCAL

LCTPC

CLICPix

KPIX

SDHCAL



SOI

RPC Muon

TPAC

Dual Readout

GEM DHCAL

Silicon ECAL

VIP

Silicon ECAL  
(SiD)

(ILD)

Scintillator  
HCAL



CMOS MAPS



DEPFET

ChronoPixel

- Large collaborations: CALICE, LCTPC, FCAL
- Collection of many efforts such as vertex R&Ds
- Individual group R&D activities
- Efforts currently not directly included in the concept groups (ILD, SiD, CLICdp), which may become important for ILC in the future

FCAL



FPCCD



# Linear Collider Collaboration Detector R&D Liaison Report

Final release (Feb. 2021) at the end of the mandate of the LCC Physics & Detectors Exec. Board:

LINEAR COLLIDER COLLABORATION

DOI 10.5281/zenodo.4496000

## Detector R&D Report

FINAL VERSION

[doi:10.5281/zenodo.3749461](https://doi.org/10.5281/zenodo.3749461)

Editors

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February 2, 2021



LINEAR COLLIDER COLLABORATION  
Designing the world's next great particle accelerator

<https://doi.org/10.5281/zenodo.3749461>

- “Publicize” particular technology and to provide an update of the recent R&D efforts (through ~ 2020)
- Provides a “snapshot” for a given technology, without information on manpower needs and financial resources to reach project milestones
- Provides an entry point for new groups in order to help them learn about the current landscape of ILC R&Ds
- No specific choices are made / keep various options for technologies to realise the individual sub-detectors → advantage that technologies can be further advanced until the project is approved.

Some « New ideas »  
(not included into the  
R&D Liaison Report)  
are presented in this talk  
from ILCX2021:

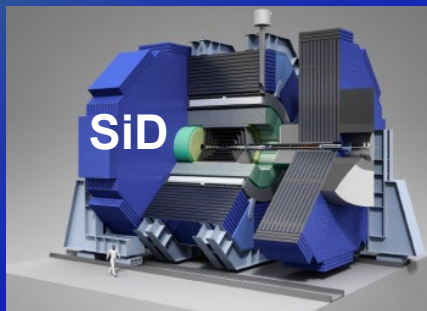
<https://agenda.linearcollider.org/event/9211/>



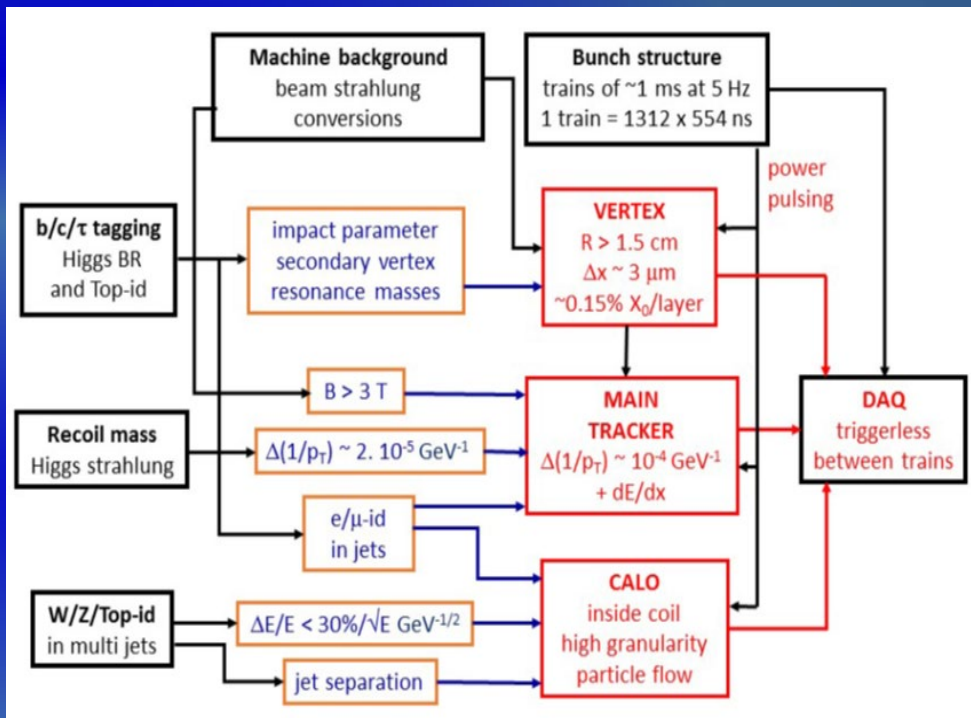
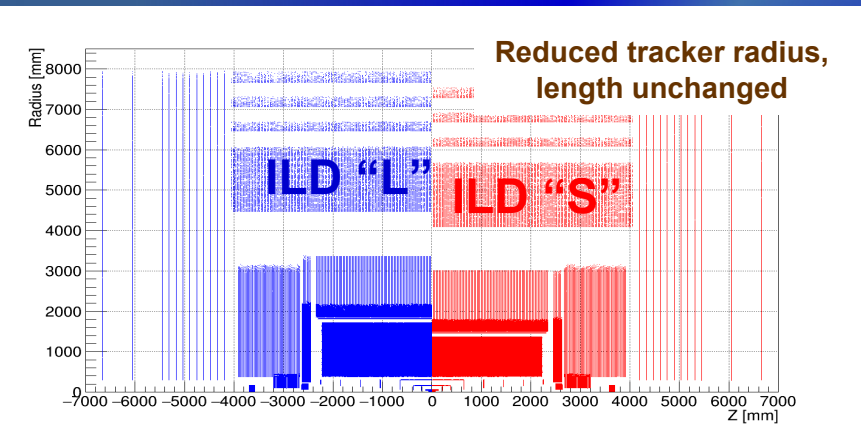
Furthermore — and as important — this keeps a broad community of R&D groups at universities and labs involved and increases the chance to arrive at the best technically possible solution when ILC has to be built.

# ILC Detector Concept Groups: ILD and SiD

- ✓ ILD: International Large Detector
- ✓ SiD: Silicon Detector



ILD Re-optimisation: **Large (L) & small (S)** options



ILD ("L" & "S")	ILD Interim Design Report: arXiv: 2003.01116	SiD	SiD Design Update: arXiv: 2110.09965
Both optimized for PFA Performance: $\sim B \cdot R_{\text{ECAL,inner}}^2$ (two-track separation @ ECAL)			
<b>B = 3.5 T / 4 T</b>		<b>B = 5 T</b>	
<b>R<sub>ECAL,inner</sub> = 1.8 / 1.46 m</b>		<b>R<sub>ECAL,inner</sub> = 1.27 m</b>	
<b>Si + TPC tracking</b> <b>Outer radius: 1.77 / 1.43 m</b>		<b>Silicon Tracking only</b> <b>Outer radius: 1.22 m</b>	



# ILD vs SiD Tracking: Two Complementary Approaches

## ILD: Silicon + Gaseous Tracking

- long barrel of 3 double layers of Si-pixels

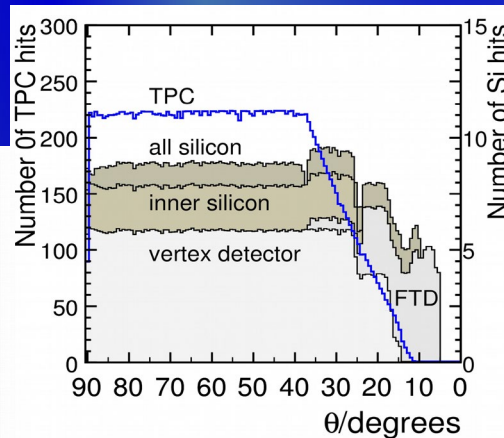
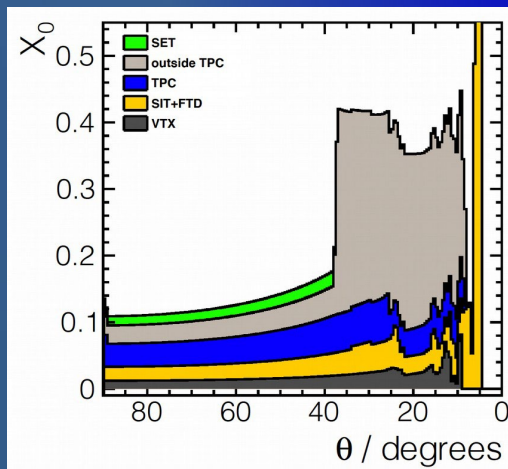
$$0.3\% X_0 / \text{layer}, \sigma_{sp} \lesssim 3 \mu m$$

**VERTEXING:**

- Intermediate **Si-tracker (SIT, SET, FTD)**
  - SIT/FTD: silicon pixel sensors (e.g. CMOS)
  - SET: silicon strip sensors
- Time Projection Chamber with MPGDs**
  - High hit redundancy (200 hits / track)
    - 3D tracking / pattern recognition;
    - dE/dx information for PID

**TRACKING:**

**ILD:**



Still a lot of opportunities in ILD/SiD optimization : physics goals, software developments and technology options

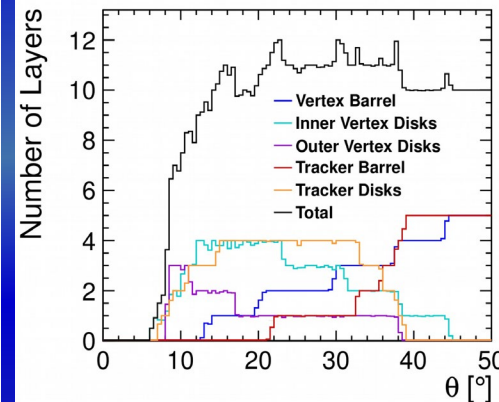
## SiD: All-Silicon Tracking

- short barrel of 5 single layers of Si-pixels

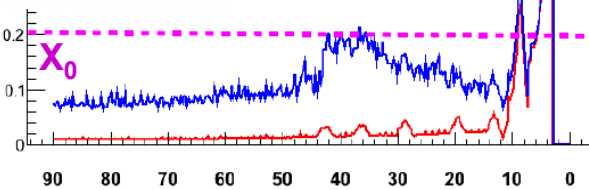
$$0.15\% X_0 / \text{layer}, \sigma_{sp} \lesssim 3-5 \mu m$$

- 5 layers Silicon-strip tracker** (25um strips, 50 um readout pitch)
  - Fewer highly precise hits (max. 12)
  - Robustness, single bunch time stamping

**SiD:**



**Vertex detector**  
**Strip detector**



# Vertex Technologies for Linear Collider: State-of-the-Art

- Exploiting the ILC low duty cycle  $0(10^{-3})$ : triggerless readout, power-pulsing
- Readout strategies:**
  - continuous during the train with power cycling → mechanic. stress from Lorentz forces in B-field
  - delayed after the train → either  $\sim 5\mu\text{m}$  pitch for occupancy or in-pixel time-stamping

## Physics driven requirements

$\sigma_{\text{s.p.}}$  **2.8 $\mu\text{m}$**

Material budget **0.15%  $X_0$ /layer**

r of Inner most layer **16mm**

## Running constraints

→ Air cooling

→ beam-related background

→ radiation damage

## Sensor specifications

Small pixel  **$\sim 16\mu\text{m}$**

Thinning to **50  $\mu\text{m}$**

low power **50 mW/cm<sup>2</sup>**

fast readout  **$\sim 1\mu\text{s}$**

radiation tolerance

**$\leq 3.4 \text{ Mrad/year}$**

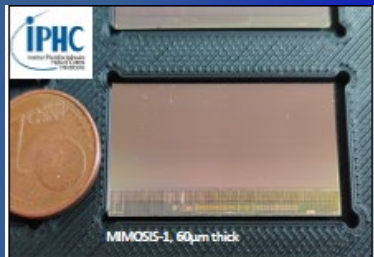
**$\leq 6.2 \times 10^{12} n_{\text{eq}} / (\text{cm}^2 \text{ year})$**

Technology	FPCCD	DEPFET	SOI	CMOS	iLGAD
Added value (example)	Very granular	Low material budget	2 tier process (high density $\mu\text{circuits}$ )	Industry evolution	PID

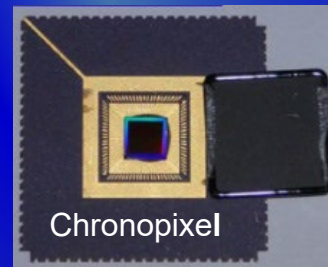
**CMOS (CPS):** continuous readout, stitching (STAR, ALICE)

**Chronopixel:** delayed readout, monolithic CMOS, 50  $\mu\text{m}$  thick

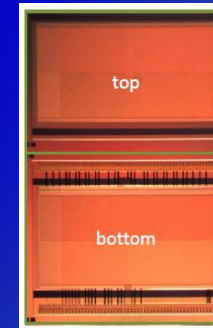
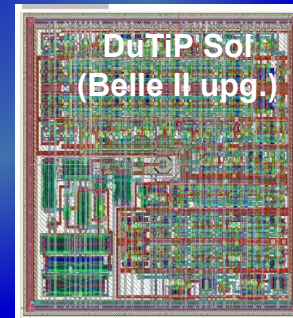
**SOI:** delayed / continuous readout; suited for 3D integration



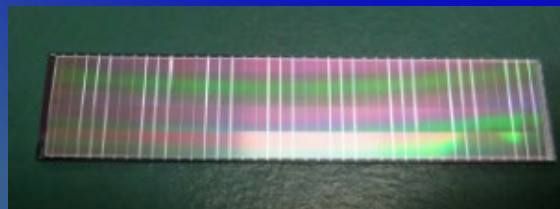
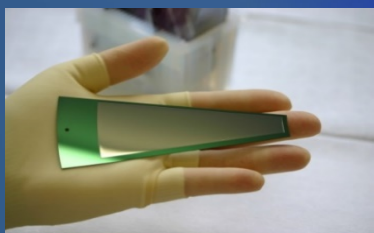
**DEPFET:** continuous readout, 75 / 50  $\mu\text{m}$  thick (Belle II)



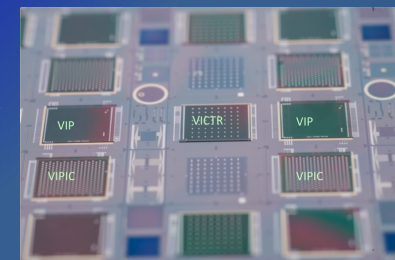
**Fine pixel CCD:** delayed readout, 5  $\mu\text{m}$  pitch, 50  $\mu\text{m}$  thickness



**Sol-based 3D integration:** rely on high-density in-pixel circuitry, with double-tier "3D" in CMOS TJ 180nm process



**3D Integration** (in-pixel data processing, on-hold): MWR in 2010, VIP(ILC)





# Vertex Technologies for Linear Collider: CMOS Evolution

A. Besson @ILCX2021

	ULTIMATE STAR-PXL	ALPIDE ALICE-ITS	MIMOSIS CBM-MVD	PSIRA proposal ILD-VXD
Data taking	2014-2016	>2021-2022	>2021	>2030
Technology	AMS-opto 0.35 $\mu\text{m}$	<b>0.18 <math>\mu\text{m}</math></b>	0.18 $\mu\text{m}$	0.18 $\mu\text{m}$ (conservative) < 0.18 $\mu\text{m}$ ?
Architecture	Rolling shutter + sparsification + binary output	<b>Asynchronous r.o. In pixel discr.</b>	Asynchronous r.o. In pixel discr.	Asynchronous r.o. (conservative)
Pitch ( $\mu\text{m}^2$ ) / Sp. Res.	20.7 x 20.7 / 3.7	27 x 29 / 5	22 x 33 / <5	$\sim 22$ / $\sim 4$
Time resolution ( $\mu\text{s}$ )	$\sim 185$	<b>5-10</b>	5	<b>1-4</b>
Data Flow		$\sim 10^6$ part/cm <sup>2</sup> /s Peak data rate $\sim 0.9$ Gbits/s	peak hit rate @ $7 \times 10^3$ /mm <sup>2</sup> /s <b>&gt;2 Gbits/s output (20 inside chip)</b>	$\sim 375$ Gbits/s (instantaneous) $\sim 1166$ Mbits / s (average)
Radiation	O(50 kRad)/year	$2 \times 10^{12}$ $n_{\text{eq}}$ /cm <sup>2</sup> 300 kRad	$3 \times 10^{13}$ $n_{\text{eq}}$ /cm <sup>2</sup> /yr & 3 MRad/yr	O(100 kRad)/year & O( $1 \times 10^{11}$ $n_{\text{eq}}$ (1MeV)) /yr
Power (mW/cm <sup>2</sup> )	< 150 mW/cm <sup>2</sup>	<b>&lt; 35 mW/cm<sup>2</sup></b>	< 200 mW/cm <sup>2</sup>	$\sim 50$ -100 mW/cm <sup>2</sup> + Power Pulsing
Surface	2 layers, 400 sensors, 360x10 <sup>6</sup> pixels 0.15 m <sup>2</sup>	7 layers, 25x10 <sup>3</sup> sensors <b>&gt; 10 m<sup>2</sup></b>	4 stations Fixed target	3 double layers 10 <sup>3</sup> sensors (4cm <sup>2</sup> ) 10 <sup>9</sup> pixels $\sim 0.33$ m <sup>2</sup>
Mat. Budget	$\sim 0.39$ % $X_0$ (1st layer)	$\sim 0.3$ % $X_0$ / layer		$\sim 0.15$ -0.2 % $X_0$ / layer
Remarks	1 <sup>st</sup> CPS in colliding exp.	(with CERN)	Vacuum operation Elastic buffer	Evolving requirements

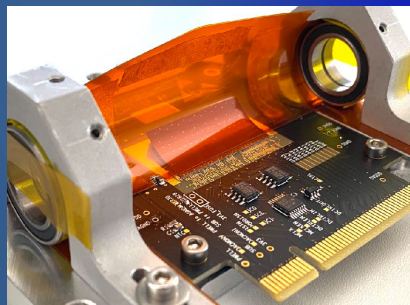
Today, most ILC R&D is focused on sensor designs  
→ Sensor's contribution to the total  $X_0$  is  
15-30% (majority cables + cooling + support)

ILC Challenges (beam bkg., cooling, material budget) needs to be addressed by emerging R&D's:

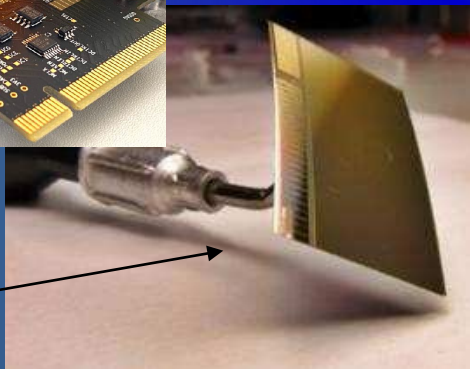
- ✓ Beam related (beamstrahlung) bkg. suppression → time stamping towards a few 100 ns (bunch-tagging)
- ✓ Further intergration &  $X_0$  reduction → reduce impact of mechanical supports, services, overlap of modules/ladders (e.g. Mu3e /ALICE studies on Kapton support structures, bent sensors)

**ALICE-ITS3 upgrade drives the R&D:**

**180 nm CMOS technology: VALIDATED**



ALPIDE@ALICE  
ITS-3 (bending  
50  $\mu\text{m}$  sensor)

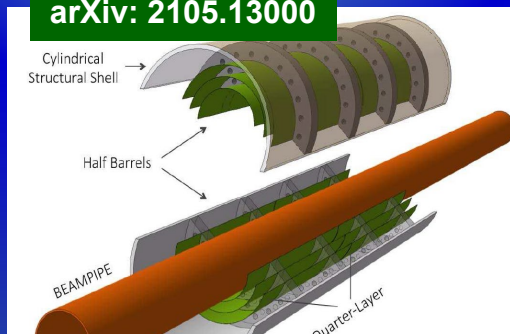


MIMOSIS @  
CBM-MVD

**Bending thin Si-layers (MAPS):**

Truly cylindrical, supportless CPS  
for ALICE-ITS3 upgrade (65 nm)

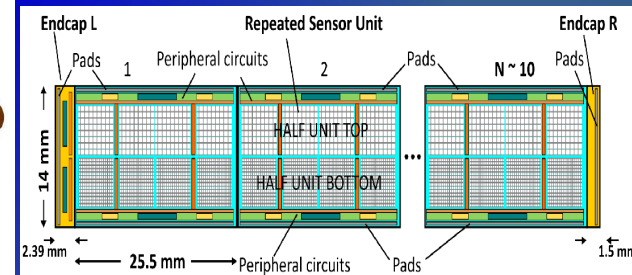
arXiv: 2105.13000



<https://indico.cern.ch/event/1071914/>

**Industrial stitching & large surfaces for low-mass detect.:**

using several reticles from the same wafer  
(possible with both 180 and 65 nm)



➤ submission (ER1, Q1 2022):  
stitching exploration

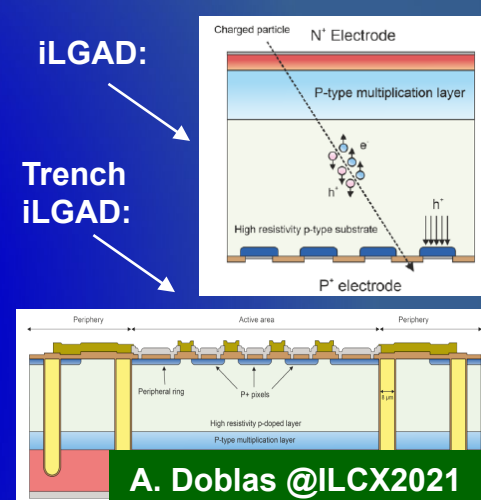
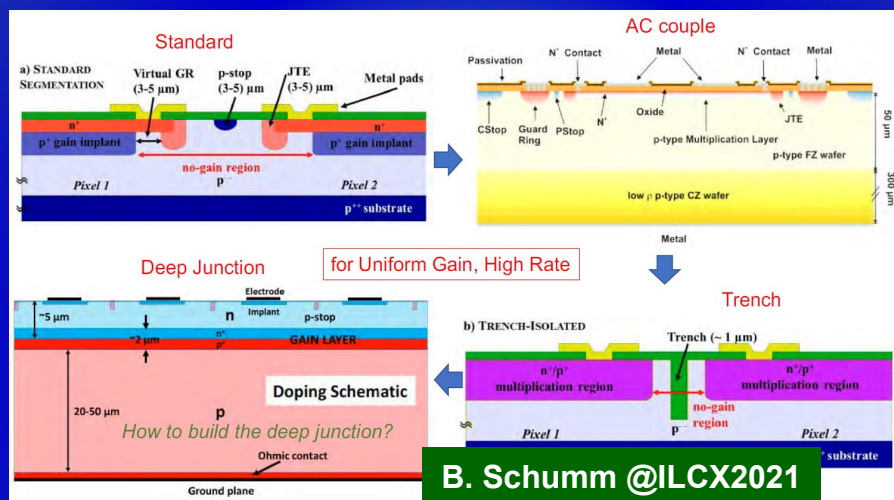
# Silicon Tracking Conceptual Studies for ILC

Not much dedicated development work recently on Silicon tracking technologies

→ Baseline solution: **silicon-microstrip tracker**; also some enabling technologies (e.g. based on LGAD concept)

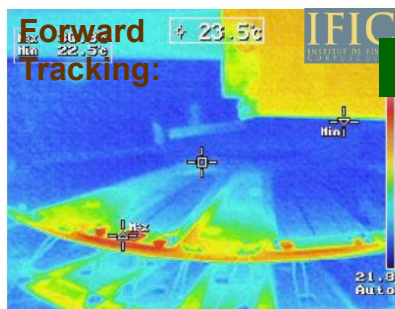
**Timing Detectors open up 4D (and 5D) tracking** → ATLAS/CMS upgrades include several m<sup>2</sup> of **LGADs**:

- ✓ Large area detectors
- ✓ High-precision tracking  
→ a few  $\mu\text{m}$  per layer
- ✓ High-precision timing  
→ tens of ps per layer
- ✓ Optimal geometrical acc. (large fill-factor).
- ✓ Low material (50  $\mu\text{m}$  thickness per plane).



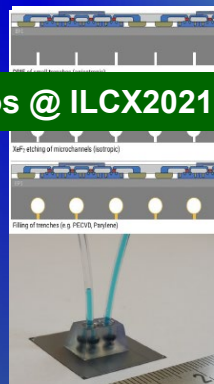
**Readout ASICs (power dissipation) may limit the intrinsic sensor performance**

→ power pulsing to reduce energy consumption or the use of microchannels to complement air cooling



Thermal management optimization strongly linked with supporting structure desing

**M. Vos @ILCX2021**



A pattern of small trenches (3 x 10  $\mu\text{m}$ ) is etched on the backside of the pixel detector

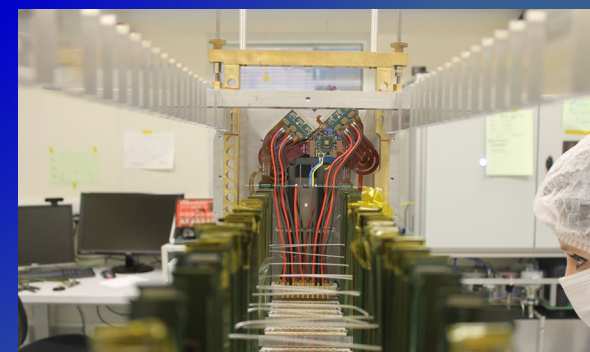
Microchannels are etched isotropically with XeF<sub>2</sub>.

A thin film of parylene (5  $\mu\text{m}$ ) seals the microchannels. It is finally cured by a thermal cycle.

M. Boscardin et al., NIMA, 2013  
L. Andricek et al., JINST 11 (2016) P06018  
C. Lipp, MSc Thesis, EPFL, 2017  
I. Beralovic et al., JINST 13 (2018) C01023

**Working MALTA CMOS sensor with integrated  $\mu$ -channels:**

**Ultra-light microchannel cooling:**



**LHCb VELO: P. Collins @ILCX2021; arXiv: 2112.12763**

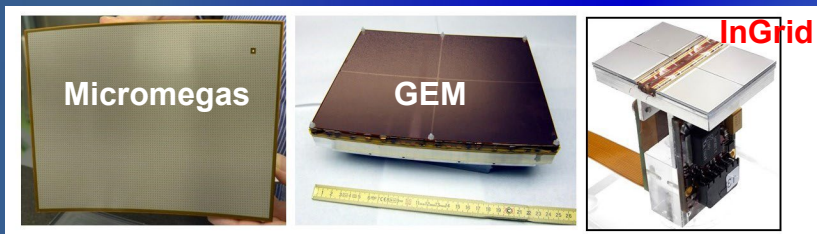


# Gaseous Tracking: TPC with MPGD-based Readout

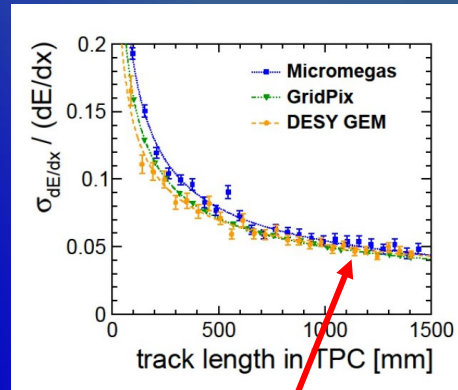
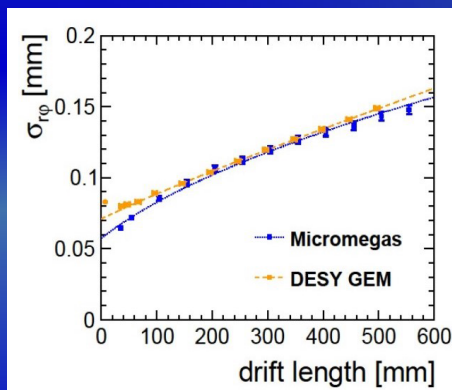


Three MPGD options are foreseen for the ILC-TPC:

- Wet-etched / Laser-etched GEMs
- Resistive Micromegas with dispersive anode
- GEM + CMOS ASICs, « GridPix » concept (integrated Micromegas grid with Timepix chip)



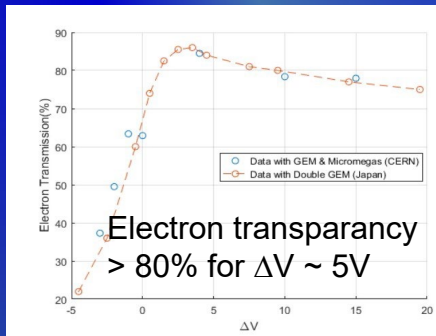
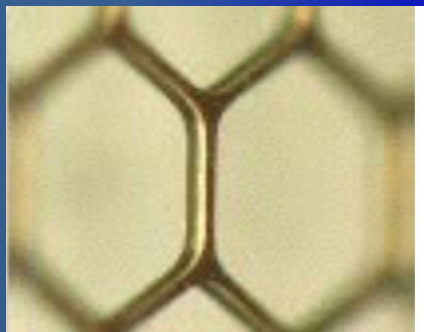
Spatial resolution of  $\sigma_T \sim 100 \mu\text{m}$  and  $dE/dx$  res.  $< 5\%$  have been reached with GEM, MM and InGrid)



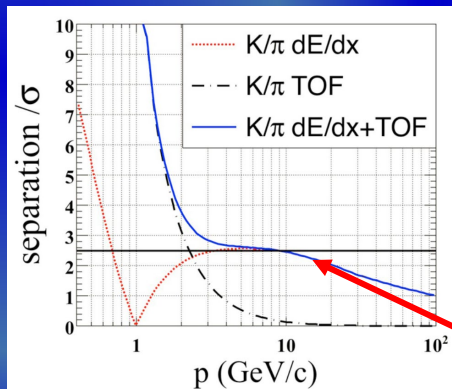
arXiv: 2003.01116

ILC: gating scheme, based on large-aperture GEM

- Machine-induced background and ions from gas amplific.
- Exploit ILC bunch structure (gate opens 50 us before the first bunch and closes 50 us after the last bunch)



Electron transparency  
 $> 80\%$  for  $\Delta V \sim 5V$

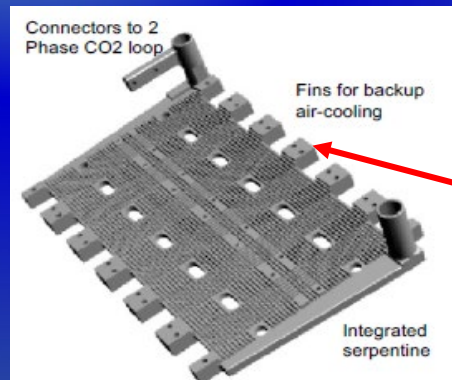


$dE/dx \sim < 4\%$  can be achieved with Gridpix (cluster-counting)

Added value of TIME information for ILC:  
 $dE/dx$  combined with ToF (SiW-ECAL) for K-PID

CHALLENGES / FUTURE PLANS:

- ✓ Common modules with a final design (with gating)
- ✓ Optimization of cooling & material budget
- ✓ GridPix development and production



3D-printed monolithic cooling plate for a TPC using 2-phase CO<sub>2</sub>

P. Colas @ ILCX2021

# Gaseous Tracking: Towards Pixel ("GridPix") TPC

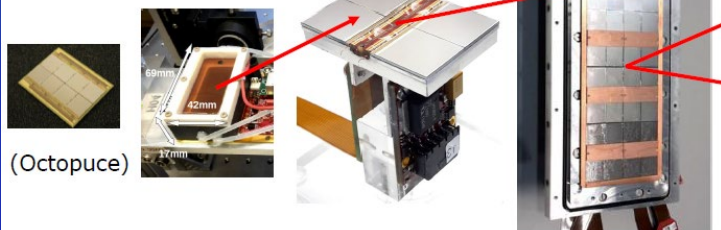
To readout ILC TPC with GridPixes:  $\sim 120$  chips/ mod.;  
240 mod./endcap ( $10 \text{ m}^2$ )  $\rightarrow \sim 50000$  GridPixes

Quad board (Timepix3) as a building block  
 $\rightarrow$  8-quad detector with a field cage



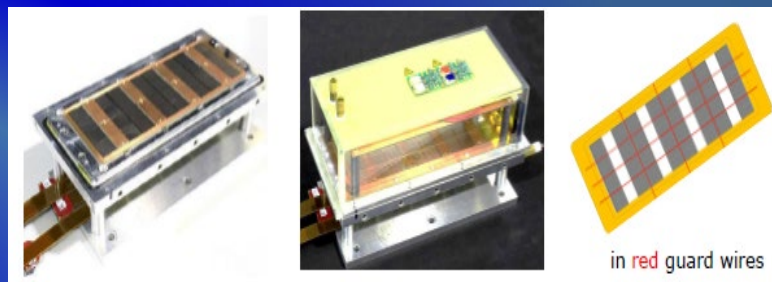
**A PIXEL TPC  
IS REALISTIC!**

NIM A956 (2020) 163331



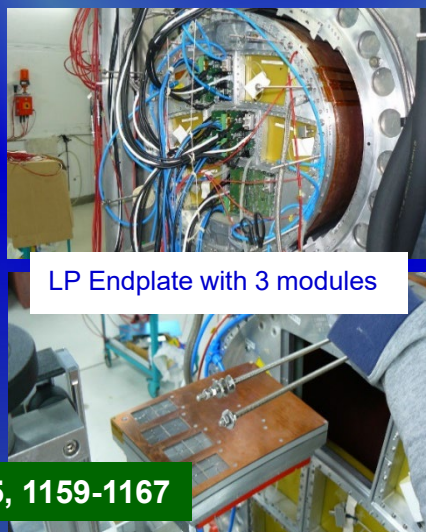
(TimePix1)	TPX3 chip	Quad	Module
(2007-14)	2017	2018	2019

J. Kaminski @ ILCX2021

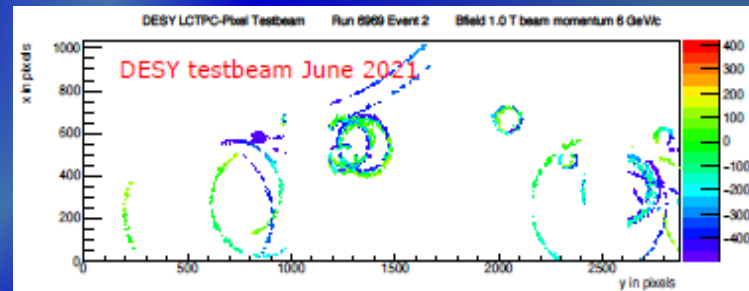


DESY Test-Beam in 2021:

**3 modules for Large TPC @ DESY: 1 x 96 and 2 x 32 GridPixs**  
320  $\text{cm}^2$  active area, 10,5 M. channels, new SRS Readout system



IEEE TNS 64 (2017)5, 1159-1167



**Physics properties of pixel TPC:**

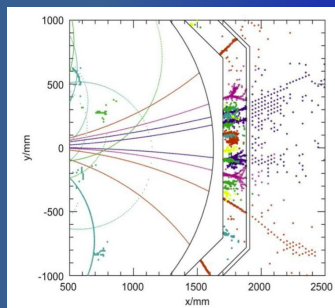
- Improved  $dE/dx$  by cluster counting
- Improved meas. of low angle tracks
- Excellent double track separation
- Lower occupancy @ high rates
- Fully digital read out (TOT)



# Particle Flow Calorimeters: CALICE Collaboration

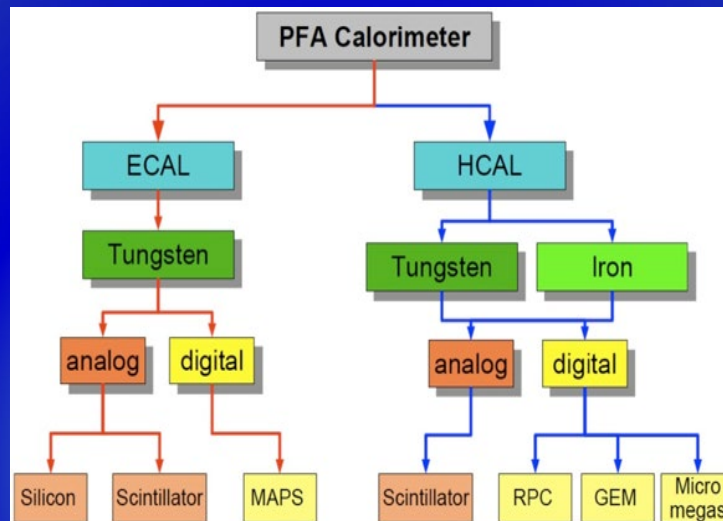
Development and study of **finely segmented / imaging calorimeters**: initially focused on the ILC, now widening to include developments of all imaging calorimeters, e.g. CMS HGCAL for Phase II):

**Imaging Calorimetry** → high granularity (in 4D), efficient software (PFA).



**Issues**: overlap between showers, complicated topology, sep. “physics event” from beam-induced bkg.

Example: **ILD detector for ILC**, proposing **CALICE** collaboration tech.



Mixture of **matured concepts** and **advanced ideas**:

**MATURED (CALICE)**:

- SiW-ECAL
- SciW-ECAL
- AHCAL
- DHCAL (sDHCAL)

→ (Almost) ready for large-scale prototype

→ Prepare for quick realization of 4-5 years to real detector

**ADVANCED (beyond CALICE)**:

- MAPS ECAL
- Dual-readout ECAL
- LGAD ECAL (CALICE)

→ Evaluate additional physics impact to ILC experiment

→ Needs intensive R&D effort to realize as real detector

	ECAL option	ECAL option	HCAL option	HCAL option
Active layer	silicon	scint+SiPM	scint+SiPM	glass RPC
Absorber	tungsten	tungsten	steel	steel
Cell size (cm×cm)	0.5×0.5	0.5×4.5	3×3	1×1
# layers	30	30	48	48
Readout	analog	analog	analog	Semi-dig (2 bits)
Depth # ( $X_0/\Lambda_{\text{int}}$ )	24 $X_0$	24 $X_0$	5.5 $\Lambda_{\text{int}}$	5.5 $\Lambda_{\text{int}}$
# channels [ $10^6$ ]	100	10	8	70
Total surface	2500	2500	7000	7000

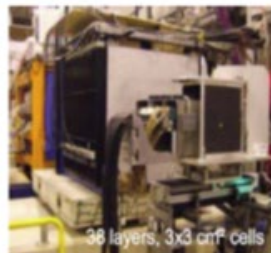
# Particle Flow Calorimeters: CALICE Collaboration

Si-W ECAL

Sc-W ECAL

Sc-Fe(W) AHCAL

GRPC-Fe DHCAL



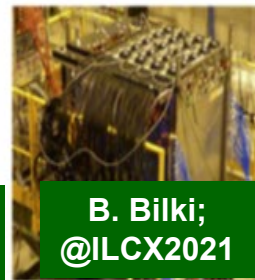
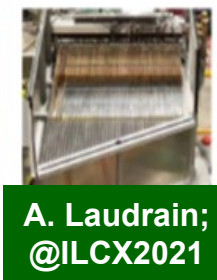
← Proof-of-principle with first generation physics prototypes (2003-2012)

Si-W ECAL

Sc-W ECAL

Sc-Fe AHCAL

GRPC-Fe SDHCAL

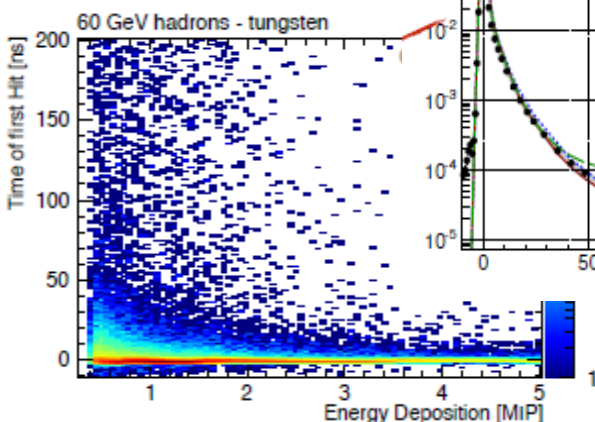
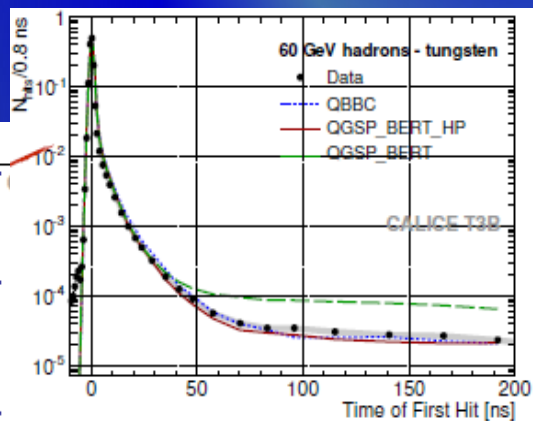


Scalability tests with 2<sup>nd</sup> generation (>2010) technological prototypes (power pulsing, compact mechanical design, embedded electronics, assembly, calibration approaches) →

## ➤ Timing measurement for shower development (from 4D to 5D):

Today's CALICE prototypes (SiW ECAL, AHCAL) provides unprecedented granularity and cell-by-cell ns-level timing for validation hadronic models on different readout technologies (gas, silicon, schint.)

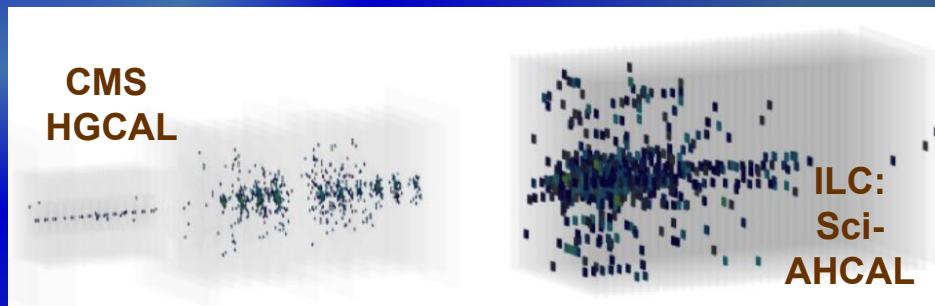
JINST9 (2014) P07022



→ improve GEANT simulation models

## ILC AHCAL & CMS HGCAL common test-beam

CMS  
HGCAL



CMS HGCAL has measured **evoluton of hadronic showers in the time domain** with ~80ps accuracy (50ps TDC binning)

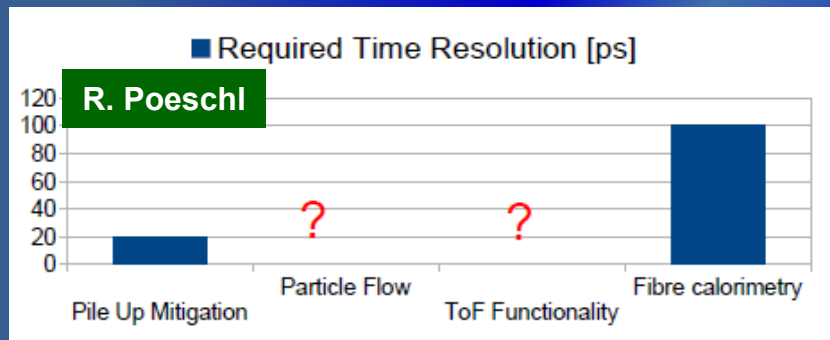


# Imaging Calorimeters: The 5<sup>th</sup> Dimension ?

Impact of 5D calorimetry (x,y,z, energy, time) needs to be evaluated more deeply to understand optimal time acc.

## What are the real goals (physics wise)?

- Mitigation of pile-up (basically all high rates)
- Support for full 5D PFA → uncharted territory
- Calorimeters with ToF functionality in first layers?
- Longitudinally unsegmented fibre calorimeters



## Replace (part of) ECAL with LGAD for O(10 ps) timing measurement

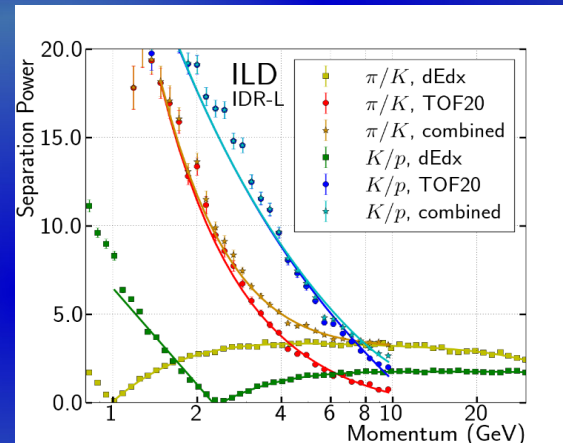
20 ps TOF per hit can separate  $\pi/k/p$  up to 5-10 GeV

T. Suehara @ILCX2021



Timing resolution  
Is affected by noise

Sensor	Amp. th.	Time reso.
S8664-50K (inverse)	20 mV	123 psec
	40 mV	63 psec
S2385 (normal)	20 mV	178 psec
	40 mV	89 psec



✓ Trade-off between power consumption and timing capabilities (maybe higher noise level)

**SDHCAL R&D: improved timing with**  
replacement of RPC with MRPC → O(20-100) ps

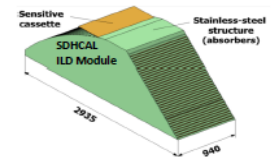
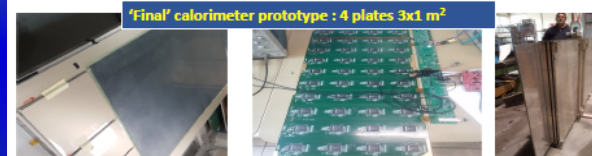
✓ Timing in calorimeters / energetic showers?

→ intelligent reconstruction using O(100) hits & NN can improve “poor” single cell timing

→ can help to distinguish particle types:  
usable for flavour tagging (b/c/s),  
long-lived searches (decaying to neutrals),  
enhance  $\sigma(E) / E$

### R&D Goals

- Come as close as possible to the final ILD SDHCAL design
- Try new feature that may bring additional assets to PFA such as timing (RPC→MRPC)
- Compare with SDHCAL prototype performance



I. Laktineh

### Timing in SDHCAL

- Discriminate neutron contribution
- Better separate hadronic showers (improved-PFA)

4-gap MRPC could reach 100 ps resolution.  
Small ASU containing 4 petrioc ASIC has been conceived and produced in collaboration with CEPC



# Imaging Calorimeters: The 5<sup>th</sup> Dimension ?

Impact of 5D calorimetry (x,y,z, energy, time) needs to be evaluated more deeply to understand optimal time acc.

## What are the real goals (physics wise)?

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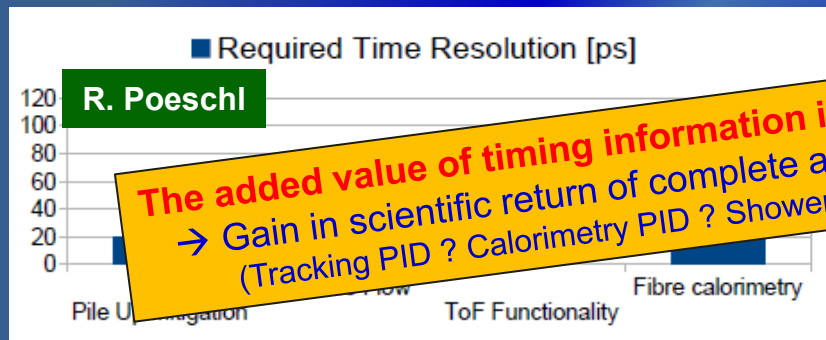
20 ps TOF per hit can separate  $\pi/k/p$  up to 5-10 GeV

T. Suehara @ILCX2021

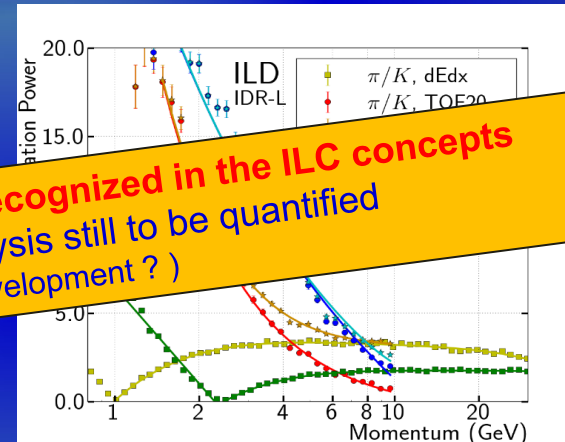


Timing resolution  
Is affected by noise

Sensor	Amp. th.	Time reso.
S8664-50K (inverse)	20 mV	123 psec
	40 mV	63 psec
S2385 (normal)	20 mV	178 psec
	40 mV	89 psec



**The added value of timing information is recognized in the ILC concepts**  
→ Gain in scientific return of complete analysis still to be quantified  
(Tracking PID ? Calorimetry PID ? Shower development ?)



✓ Trade-off between power consumption and timing capabilities (maybe higher noise level)

**SDHCAL R&D: improved timing with**  
replacement of RPC with MRPC → O(20-100) ps

✓ Timing in calorimeters / energetic showers?

→ intelligent reconstruction using O(100) hits & NN can improve “poor” single cell timing

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usable for flavour tagging (b/c/s),  
long-lived searches (decaying to neutrals),  
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**R&D Goals**

- Come as close as possible to the final ILD SDHCAL design
- Try new feature that may bring additional assets to PFA such as timing (RPC→MRPC)
- Compare with SDHCAL prototype performance

**'Final' calorimeter prototype : 4 plates 3x1 m<sup>2</sup>**

**Timing in SDHCAL**

- Discriminate neutron contribution
- Better separate hadronic showers (improved-PFA)

4-gap MRPC could reach 100 ps resolution.  
Small ASU containing 4 petrioc ASIC has been conceived and produced in collaboration with CEPC

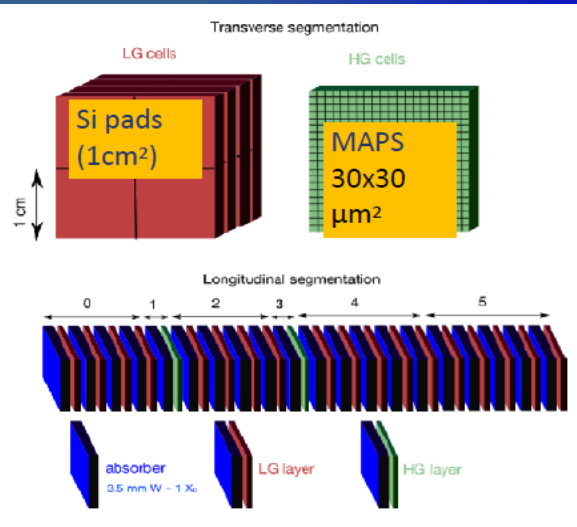
**I. Laktineh**



# New Trends: Ultra-High Granularity (MAPS ECAL)

CMOS Sensors for calorimetry → Synergies between **LC Detector R&D** and **ALICE FoCAL**

**ALICE FoCAL: 24 layer MIMOSA CMOS sensor calorimeter Si-W stack**



**Forward electromagnetic and hadronic calorimeters;**

- ✓ FoCal-E: high-granularity Si-W sampling calorimeter → direct  $\gamma$ ,  $\pi^0$
- ✓ FoCal-H: Pb-Sc sampling calorimeter for photon isolation and jets

Digital ECAL prototype:

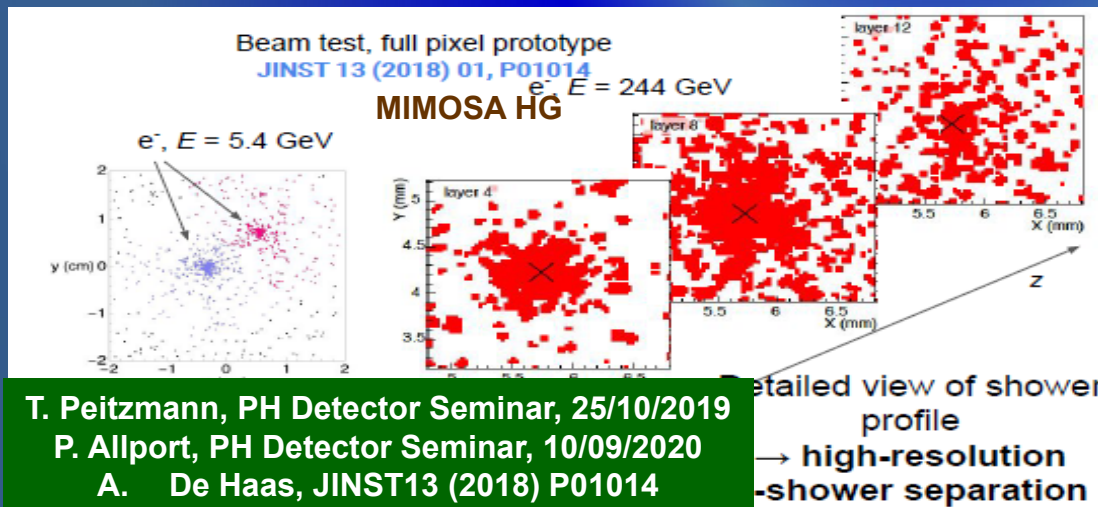
- number of pixels above threshold ~ deposited energy
- Monolithic Active Pixel Sensors (MAPS) PHASE2/MIMOSA23 with a pixel size:  $30 \times 30 \mu\text{m}^2$
- 24 layers of 4 sensors each: active area  $4 \times 4 \text{ cm}^2$ , 39 M pixels
- 3 mm W absorber for 0.97  $X_0$  per layer  $R_M \sim 11 \text{ mm}$

FoCAL: assuming  $\approx 1 \text{ m}^2$  detector surface

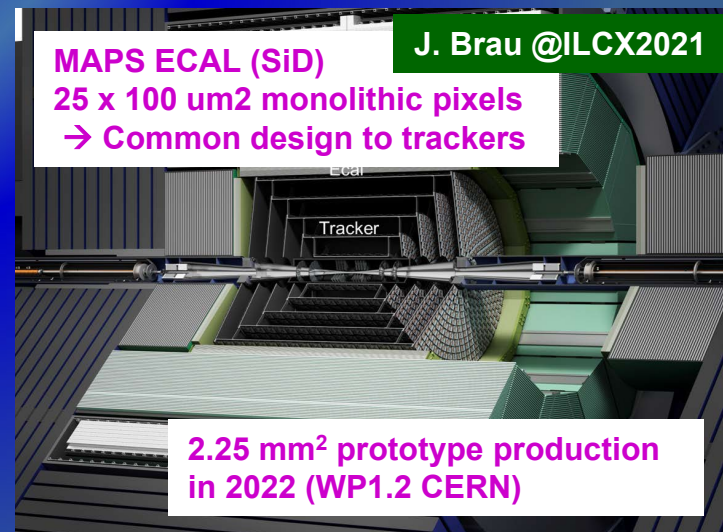
**A. Rossi @ ICHEP2020**

	LG	HG
pixel/pad size	$\approx 1 \text{ cm}^2$	$\approx 30 \times 30 \mu\text{m}^2$
total # pixels/pads	$\approx 2.5 \times 10^5$	$\approx 2.5 \times 10^9$
readout channels	$\approx 5 \times 10^4$	$\approx 2 \times 10^6$

Could be a unique tool to improve shower simulation ...

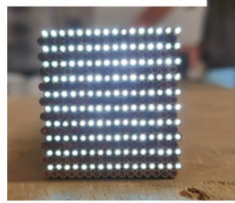


T. Peitzmann, PH Detector Seminar, 25/10/2019  
P. Allport, PH Detector Seminar, 10/09/2020  
A. De Haas, JINST13 (2018) P01014



# New Ideas: Dual-Readout Calorimetry + High Granularity

Cherenkov fibres



Scintillating fibres



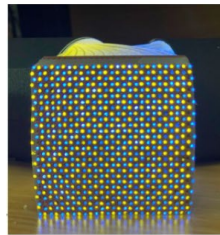
Fast signals

for relativistic  
(EM) component

Slow signals

for non-  
relativistic  
(hadronic)

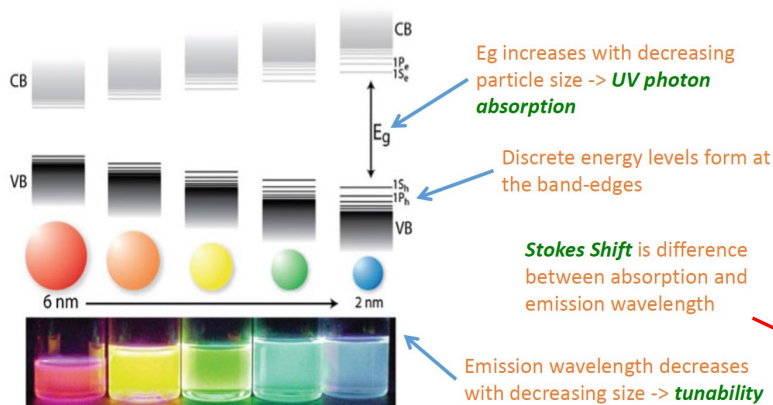
**Building  
Blocks:**



SiPM for much  
better separation  
of Ch. & Sci. light

Dual readout to capture  
Electromagnetic and hadronic  
components of shower

Quantum Confinement changes material properties when particle  
size < electron wavelength (nm-size particles -> nanoparticles)



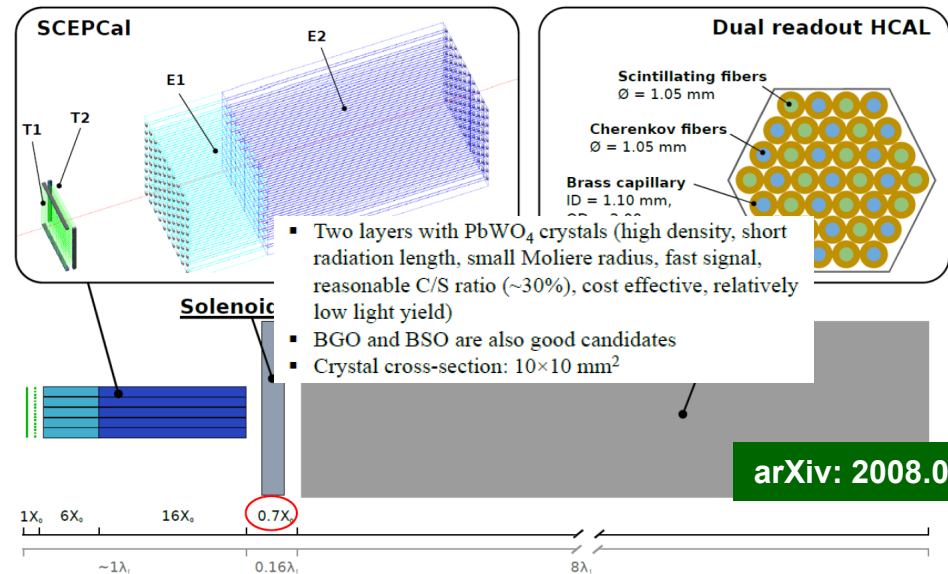
**Extensive R&D by the DREAM/RD52/IDEA collaborations**  
(Rev. Mod. Phys. 90, 025002, 2018): **an old idea in 4th ILC concept**  
→ Recent technological progress (SiPM, 3D-printed  
absorber material) enables highly granular DREAM calorimetry

✓ **Dual-readout (DRO) crystal ECAL:**

**J. Zhu @ILCX2021**

## A Segmented DRO Crystal ECAL with a DRO Fiber HCAL

arXiv:2008.00338



**Readout Detector Development R&D:**

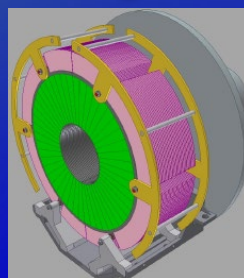
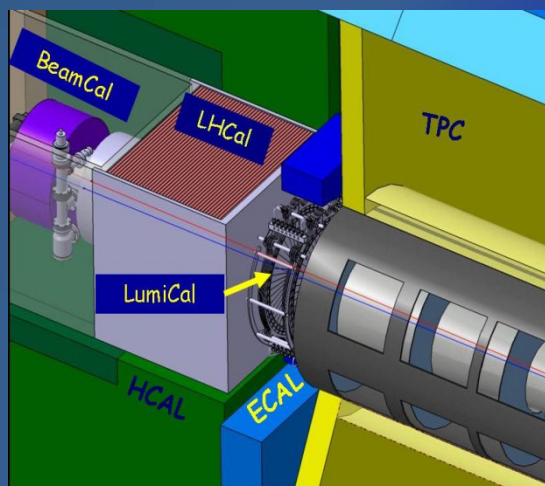
**S. Magill @ILCX2021**

R&D Focus : Optimal readout technologies for scintillation and Cherenkov signals – includes minimization of material between crystals to maximize sampling (-> *homogeneous calorimeter*)

Wavelength conversion by nanoparticles discussed  
for detection of Cherenkov light

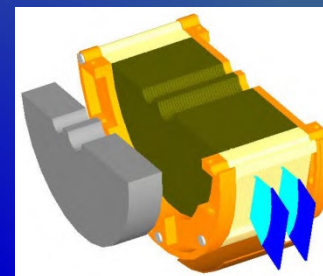


# Forward Calorimetry R&D: FCAL Collaboration



## LumiCal:

→ precise luminosity measurement  
10<sup>-3</sup> - 500 GeV @ ILC



## BeamCal:

→ inst. lumi measurement / beam tuning, beam diagnostics

**LumiCal:** Two Si-W sandwich EM calo at a ~ 2.5 m from the IP (both sides)

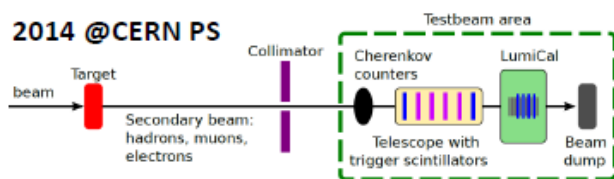
**BeamCal:** very high radiation load (up to 1MGy/ year) → similar W-absorber, but radiation hard sensors (GaAs, CVD diamond, sapphire)

**LHCAL:** sampling calo (tungsten or iron with SI) → extend HCal coverage

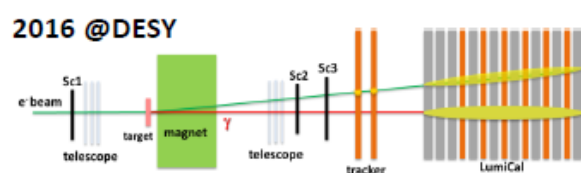
## Beam-test campaigns:

LumiCal prototypes multi-plane operation:

### 2014 @ CERN PS



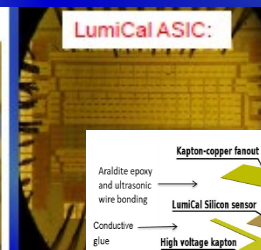
### 2016 @ DESY



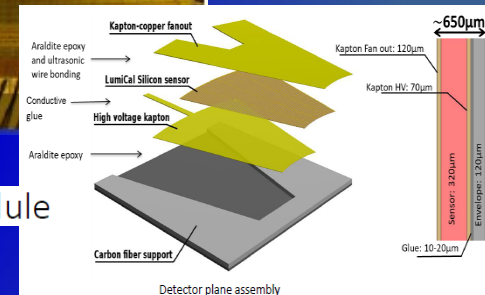
### 2020 @ DESY



A. Neagu @ ILCX2021



## LumiCal thin prototype module



## LumiCal Challenges:

- ✓ Build a ultra compact LumiCal (alignment, deformation);
- ✓ Edgeless sensors (to avoid dead areas)
- ✓ Multi-layer LumiCal prototype with new (FLAME) ASIC;

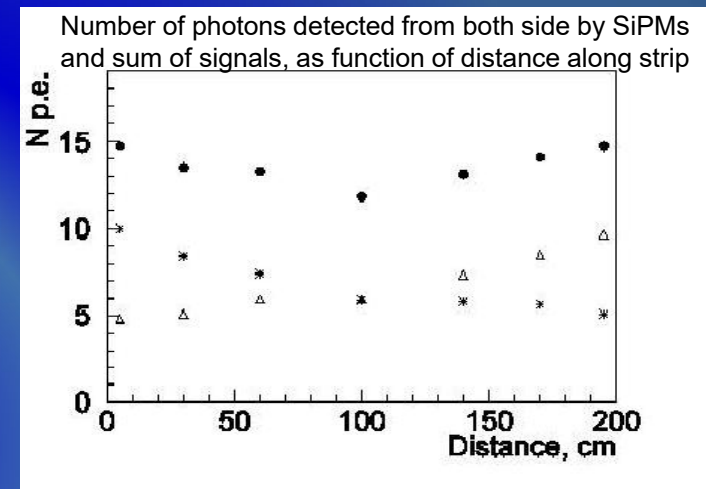
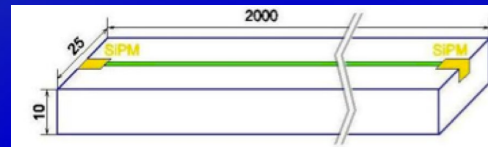
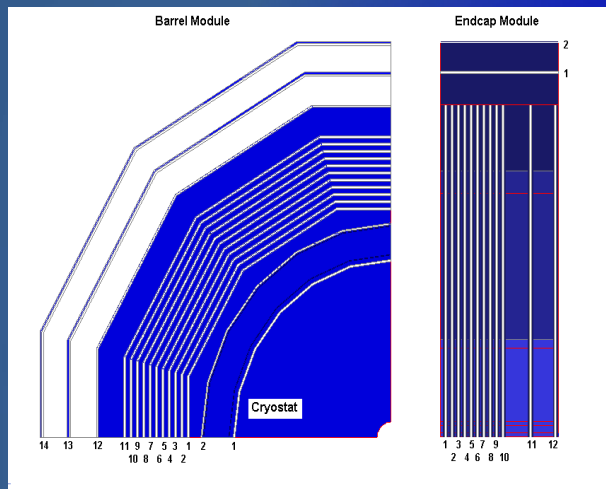
## BeamCal Challenges:

- ✓ Development of sapphire sensors with dedicated ASIC;
- ✓ Ongoing radiation damage studies (GaAs, Si diode, CVD diamond, sapphire ...)

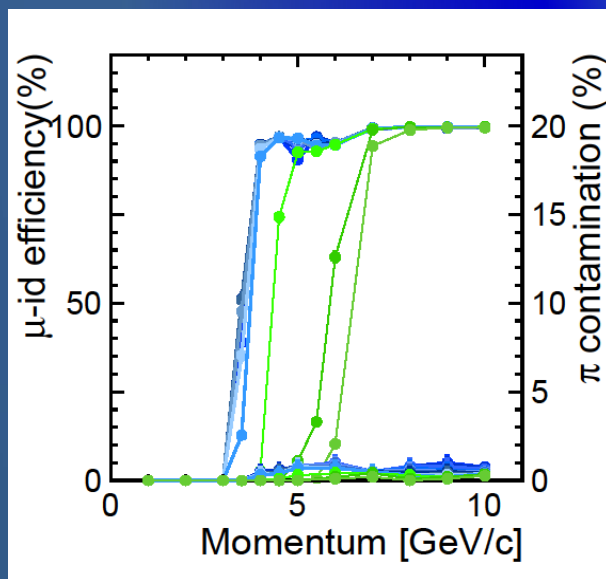
# Muon System / York Instrumentation

Efficient Muon Identification & Measurement of the Energy Leakage from Hadron Calorimeter

**Main technology (compatible with HCAL) – Scintillation strips with WLS and SiPM readout**



Muon efficiency & Pion contamination:



- ✓ **Baseline option under development:**  
→ Scintillator + WaveLengthShifter + SiPM;
- ✓ Development of the Key Elements Sc/WLS/SiPM – **Digital Silicon Photomultiplier** in CMOS technology is in progress;
- ✓ **Gas Detector - RPC** (high coordinate resolution, excellent granularity up to 1 x 1 cm<sup>2</sup> pads) → **not active for now**;
- ✓ Not many groups are participating in the Muon System Study
- ✓ No significant challenges in terms of particle fluxes and radiation environment → many technologies feasible



# ILC International Development Team Goals for 2021-2022

- ✓ Establish a preliminary list of the **ILC Pre-lab tasks and deliverables** (through WG2) and **national/regional laboratories** which might be interested in **contributing to those**;
- ✓ Establish **Pre-lab resources needs for the regional activities** and central office (**a few % of ILC cost**);
- ✓ Prepare a **preliminary proposal for the ILC Pre-lab organization and governance**;
- ✓ Finalise all the **inputs needed to set-up the Pre-lab**;

**Established in  
August 2020**

ICFA

**ILC International Development Team**  
**<https://linearcollider.org/>**

## Executive Board

<i>Americas Liaison</i>	Andrew Lankford (UC Irvine)
<i>Working Group 2 Chair</i>	Shinichiro Michizono (KEK)
<i>Working Group 3 Chair</i>	Hitoshi Murayama (UC Berkeley/U. Tokyo)
<i>Executive Board Chair and Working Group 1 Chair</i>	Tatsuya Nakada (EPFL)
<i>KEK Liaison</i>	Yasuhiro Okada (KEK)
<i>Europe Liaison</i>	Steinar Stapnes (CERN)
<i>Asia-Pacific Liaison</i>	Geoffrey Taylor (U. Melbourne)

**Working Group 1**  
Pre-Lab Setup

**Working Group 2**  
Accelerator

**Working Group 3**  
Physics & Detectors

## Proposal for the ILC Preparatory Laboratory (Pre-lab)

International Linear Collider  
International Development Team

1 June 2021

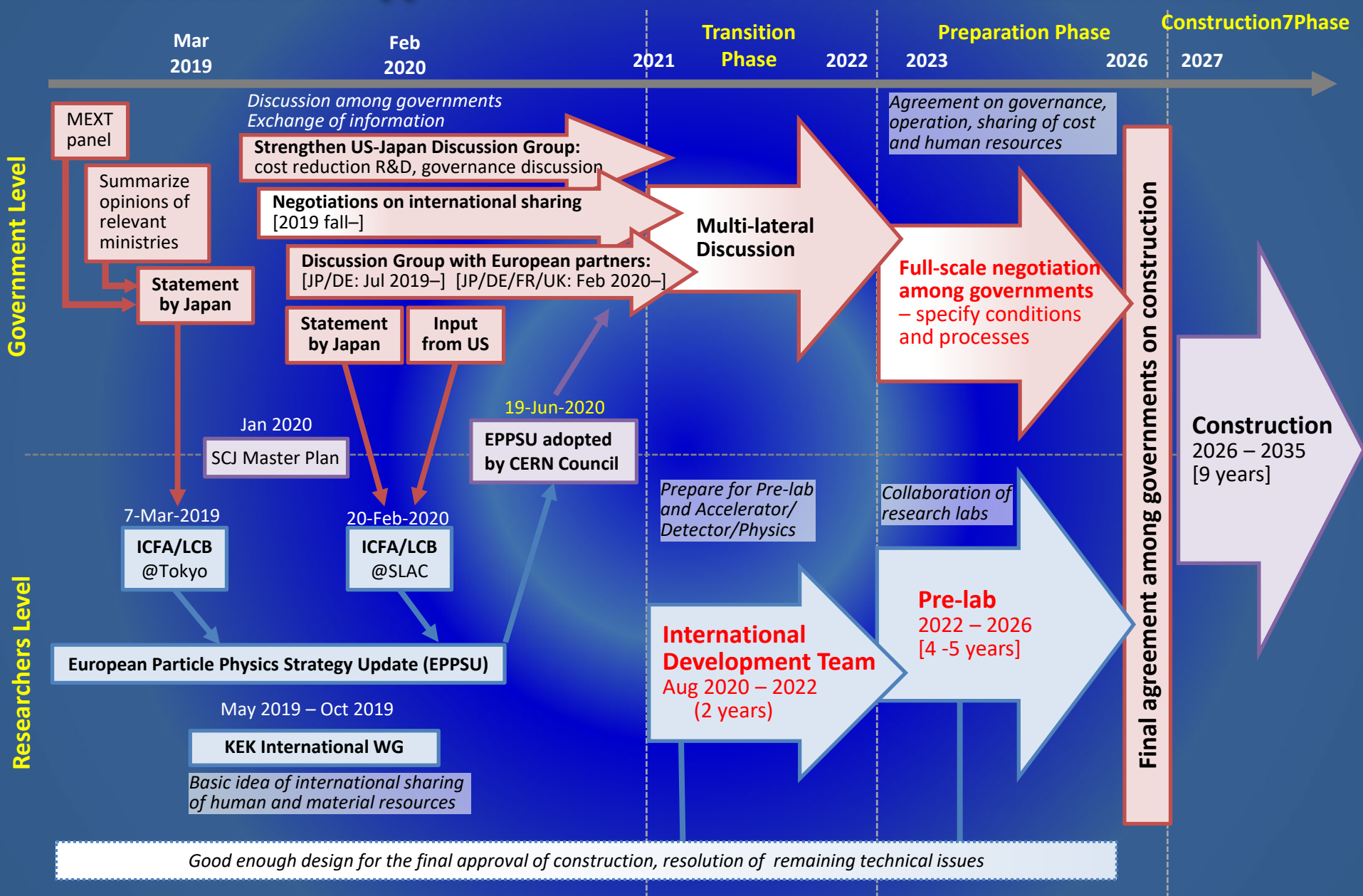
**arXiv: 2106.00602**

## Abstract

During the preparatory phase of the International Linear Collider (ILC) project, all technical development and engineering design needed for the start of ILC construction must be completed, in parallel with intergovernmental discussion of governance and sharing of responsibilities and cost. The ILC Preparatory Laboratory (Pre-lab) is conceived to execute the technical and engineering work and to assist the intergovernmental discussion by providing relevant information upon request. It will be based on a worldwide partnership among laboratories with a headquarters hosted in Japan. This proposal, prepared by the ILC International Development Team and endorsed by the International Committee for Future Accelerators, describes an organisational framework and work plan for the Pre-lab. Elaboration, modification and adjustment should be introduced for its implementation, in order to incorporate requirements arising from the physics community, laboratories, and governmental authorities interested in the ILC.

arXiv:2106.00602v1 [physics.acc-ph] 1 Jun 2021

# Processes and Approximate Timelines Towards Realization of ILC



\* ICFA: international organization of researchers consisting of directors of world's major accelerator labs and representatives of researchers

\* ILC pre-lab: International research organization for the preparation of ILC based on agreements among world's major accelerator labs such as KEK, CERN, FNAL, DESY, etc.